

CCD Image Digitizers with CDS, PGA and 10-Bit A/D

**XPEXAR** 

#### FEATURES

- 10-Bit Resolution ADC
- 18 27MHz Maximum Sampling Rate
- Correlated Double Sampling (CDS)
- Programmable Gain from 6dB to 38dB (PGA)
- Digitally Controlled Analog Offset-Calibration
- CCD Black Level Offset Compensation at Frame Rate
- CDS Clocks Sample Rising Edge or Falling Edge
- Single 5V or 3V Power Supply
- Low Power for Battery Applications:
  - XRD9855/56:
      $250/300 \text{m W} @ \text{V}_{DD} = 5.0\text{V}$  

     XRD98L55/L56:
      $120/150 \text{mW} @ \text{V}_{DD} = 3.0\text{V}$
- 50µA-Typ Current in Stand By Mode

- 3-State Digital Outputs
- ESD Protection to Over 2000V

#### APPLICATIONS

- Digital Video Camcorders
- Digital Still Cameras
- PC Video Teleconferencing
- Digital Copiers
- Infrared Image Digitizers
- CCD/CIS Imager Interface
- CCTV/Security Camera
- 2D Bar Code Readers
- Industrial Cameras

#### **GENERAL DESCRIPTION**

The XRD9855/XRD9856 are complete CCD Image Digitizers for digital cameras. The products include a high bandwidth differential Correlated Double Sampler (CDS), 8-bit digitally Programmable Gain Amplifier (PGA), 10-bit Analog-to-Digital Converter (ADC) and digital controlled black level auto-calibration circuitry.

The Come hated Double Sampler (CDS) subtracts the CCD output signalblack level from the video level. Commonmode signalnoise and powersupply noise are rejected by the differential CDS inputs tage. CDS inputs are designed to be used either differential or singleended.

The auto calibration circuit com pensates for any internaloffset of the XRD 9855 / XRD 9856 as well as black level offset from the CCD. The PGA is digitally controlled with 8-bit resolution on a linear dB scale, resulting in a gain range of 6dB to 38dB with 0.125dB per LSB of the gain code.

The PGA and black level auto-calibration are controlled through a simple 3-wire serial interface. The timing circuitry is designed to enable users to select a wide variety of available CCD and image sensors for their applications.

The XRD9855/XRD9856 has direct access to the PGA output and ADC input through the pin TESTVIN. The XRD9855/XRD9856 are packaged in 48-lead surface mount TQFP to reduce space and weight, and suitable for hand-held and portable applications.

Part No.	Package	Temperature Range	Operating Power Supply	Maximum Sampling Rate
XRD9855AIV	48 Lead TQFP (7 x 7 x 1.4 mm)	-40°C to 85°C	5.0V	18 MSPS
XRD98L55AIV	48 Lead TQFP (7 x 7 x 1.4 mm)	-40°C to 85°C	3.0V	18 MSPS
XRD9856AIV	48 Lead TQFP (7 x 7 x 1.4 mm)	-40°C to 85°C	5.0V	27 MSPS
XRD98L56AIV	48 Lead TQFP (7 x 7 x 1.4 mm)	-40°C to 85°C	3.0V	27 MSPS

#### **ORDERING INFORMATION**

Rev. 1.01

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Figure 1. XRD9855/XRD9856 Simplified Block Diagram







#### **PIN DESCRIPTION – 48 pin TQFP**

Pin #	Symbol	Description
1	NC	No Connect.
2	NC	No Connect.
3	DB2	ADC Output. DB0 is the LSB, DB9 is the MSB.
4	DB3	ADC Output.
5	DB4	ADC Output.
6	DGND	Digital Output Ground.
7	$DV_DD$	Digital Output Power Supply. Must be less than or equal to V <sub>DD</sub> .
8	DB5	ADC Output.
9	DB6	ADC Output.
10	DB7	ADC Output.
11	NC	No Connect.
12	NC	No Connect.
13	DB8	ADC Output.
14	DB9	ADC Output. MSB
15	OVER	<b>Over Range Output Bit.</b> OVER goes high to indicate the ADC input voltage is greater than $V_{\text{RT}}$ .

#### Rev. 1.01



#### PIN DESCRIPTION – 48 pin TQFP (CONT'D)

Pin #	Symbol	Description
16	ŌE	Digital Output Enable (Three-State Control). Pull OE low to enable output
		drivers. Pull OE high to put output drivers in high impedance state.
17	V <sub>DD</sub>	Analog Power Supply.
18	EnableCal	Calibration Enable. Automatic offset calibration control.
19	GND	Analog Ground.
20	TESTVIN	ADC Test Input & PGA Test Output.
21	STBY1	Standby Control 1. Pull low to put chip in power down mode.
22	STBY2	<b>Standby Control 2.</b> Short to STBY1 pin if not using TESTVIN pin.
23	RESET	Chip Reset. Pull high to reset all internal registers.
24	SCLK	Shift Clock. Shift register latches SDI data on rising edges of SCLK.
25	NC	No Connect.
26	LOAD	<b>Data Load.</b> Rising edge loads data from shift register to internal register. Load must be low to enable shift register.
27	SDI	Serial Data Input.
28	V <sub>RT</sub>	Top ADC Reference. Voltage at V <sub>RT</sub> sets full-scale of ADC.
29	V <sub>RTO</sub>	Internal Bias for $V_{RT}$ . Short $V_{RT}$ to $V_{RTO}$ to use internal reference voltage.
30	V <sub>DD</sub>	Analog Power Supply.
31	In_Neg	CDS Inverting Input. Connect via capacitor to CCD video output.
32	In_Pos	CDS Non-inverting Input. Connect via capacitor to CCD supply.
33	GND	Analog Ground.
34	V <sub>RBO</sub>	Internal Bias for $V_{RB}$ . Short $V_{RB}$ to $V_{RB0}$ to use internal reference voltage.
35	V <sub>RB</sub>	Bottom ADC Reference. Voltage at $V_{RB}$ sets zero scale of the ADC.
36	NC	No Connect.
37	CLAMP	CDS DC Restore Clamp. Clamps In_Pos & In_Neg to internal bias voltage.
38	SHD	CDS Clock. Controls sampling of the pixel video level.
39	SHP	CDS Clock. Controls sampling of the pixel black level.
40	RSTCCD	CCD Reset Pulse Disconnect. Used to decouple CDS during the reset pulse.
41	GND	Analog Ground.
42	CLK_POL	Clock Polarity. Controls the polarity of SHP, SHD & CLAMP.
43	V <sub>DD</sub>	Analog Power Supply.
44	SYNC	Digital output for Exar test purposes only. No connect.
45	UNDER	Under Range Output Bit. UNDER goes high to indicate the ADC input voltage is less than ${\rm V}_{\rm RB}.$
46	DBO	ADC Output. LSB
47	DB1	ADC Output.
48	NC	No Connect.

Rev. 1.01



#### DC ELECTRICAL CHARACTERISTICS – XRD9855 and XRD9856

Unless otherwise specified: DV<sub>DD</sub> = V<sub>DD</sub> = 5.0V, Pixel Rate = 18MSPS, V<sub>RT</sub> = 3.8V, V<sub>RB</sub> = 0.5V

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
CDS Performa	ance					
CDSVIN	Input Range		200	800	mV <sub>PP</sub>	Pixel (Black Level - Video Level)
BW	Small Signal Bandwidth (-3dB)		60		MHz	
SR	Slew Rate		40		V/µs	400mV Step Input
FT	Feed-through (Hold Mode)		-60		dB	
PGA Paramet	ers					
AV <sub>MIN</sub>	Minimum Gain	3.5	5	6.5	dB	
AV <sub>MAX</sub>	Maximum Gain	35.5	37	38.5	dB	
PGA n	Resolution		8		bits	Transfer function is linear steps in dB (1LSB = 0.125dB)
GE	Gain Error		5		% FS	At maximum or minimum gain setting
ADC Paramete	ers (Measured Through TESTV	N)				
ADC n	Resolution	10			bits	
f <sub>s</sub>	Max Sample Rate	27			MSPS	
DNL	Differential Non-Linearity	-1	<u>+</u> 0.75	1.2	LSB	Up to 18MHz sample rate
						(XRD9855)
DNL27	Differential Non-Linearity	-1	<u>+</u> 1.3	2.0	LSB	Up to 27MHz sample rate
						(XRD9856)
EZS	Zero Scale Error	-50		50	mV	Measured relative to $V_{RB}$
EFS	Full Scale Error			4	% FS	
V <sub>IN</sub>	DC Input Range	GND		V <sub>DD</sub>	V	$V_{IN}$ of the ADC can swing from GND to $V_{DD}$ . Input range is limited by the output swing of the PGA
V <sub>RT</sub>	Top Reference Voltage	1.5	3.8	$V_{\text{DD}}$	V	V <sub>RT</sub> >V <sub>RB</sub>
V <sub>RB</sub>	Bottom Reference Voltage	0.3	0.5	V <sub>DD</sub> -1	V	V <sub>RT</sub> >V <sub>RB</sub>
$\Delta V_{REF}$	Differential Reference Voltage	1.0	3.3	$V_{\text{DD}}$	V	
RL	Ladder Resistance	280	400	520	Ohms	
V <sub>RB</sub>	Self Bias $V_{RB} \left( V_{RB} = \frac{V_{DD}}{10} \right)$	0.4	0.5	0.6	v	V <sub>RB</sub> connected to V <sub>RBO</sub>
V <sub>RT</sub>	Self Bias $V_{RT} \left( V_{RT} = \frac{V_{DD}}{1.30} \right)$	3.5	3.8	4.1	V	V <sub>RT</sub> connected to V <sub>RTO</sub>

Rev. 1.01



#### DC ELECTRICAL CHARACTERISTICS – XRD9855 and XRD9856 (CONT'D) Unless otherwise specified: $DV_{DD} = V_{DD} = 5.0V$ , Pixel Rate = 18MSPS, $V_{RT} = 3.8V$ , $V_{RB} = 0.5V$

Symbol	Parameter	Min.	Тур.	Typ. Max.		Conditions
System Speci	fications					
DNLS	System DNL		1.0		LSB	XRD9855 up to 18 MSPS
DNL <sub>S27</sub>	System DNL 27 MSPS		1.0		LSB	XRD9856 up to 27 MSPS
INL <sub>SMIN</sub>	INL @ Minimum Gain				LSB	INL error is dominated by CDS/PGA linearity.
INL <sub>SMAX</sub>	INL @ Maximum Gain				LSB	INL error is dominated by CDS/PGA linearity.
V <sub>OS MINAV</sub>	Offset (Input Referred) @ Minimum Gain		5		mV	Offset is defined as the input pixel value-0.5 LSB required to cause the ADC output to switch from "Zero scale" to "Zero scale + 1LSB".
V <sub>OS MAXAV</sub>	Offset (Input Referred) @ Maximum Gain		1		mV	Offset is measured after calibration. Zero scale is the code in the offset register.
en <sub>MAXAV</sub>	Input Referred Noise @ Maximum Gain		0.2		mV <sub>rms</sub>	Noise depends upon gain setting of the PGA.
en <sub>MINAV</sub>	Input Referred Noise @ Minimum Gain		1.1		mV <sub>rms</sub>	Noise depends upon gain setting of the PGA.
Digital Inputs						
V <sub>IH</sub>	Digital Input High Voltage	2.0			V	
VIL	Digital Input Low Voltage			0.7	V	
IL.	DC Leakage Current		5		μA	Input Between GND and $V_{DD}$
C <sub>IN</sub>	Input Capacitance		5		pF	
Digital Outputs	S					
V <sub>OH</sub>	Digital Output High Voltage	DV <sub>DD</sub> -0.5			V	While sourcing 2mA.
V <sub>OL</sub>	Digital Output Low Voltage			0.5	V	While sinking 2mA.
l <sub>oz</sub>	High-Z Leakage	-10		10	μA	$\overline{OE}$ =1 or $\overline{STBY1}$ = $\overline{STBY2}$ = 0. Output between GND & DV <sub>DD.</sub>



#### DC ELECTRICAL CHARACTERISTICS – XRD9855 and XRD9856 (CONT'D) Unless otherwise specified: $DV_{DD} = V_{DD} = 5.0V$ , Pixel Rate = 18MSPS, $V_{RT} = 3.8V$ , $V_{RB} = 0.5V$

Symbol	Parameter		Тур.	Max.	Unit	Conditions
Digital I/O Timi	ng					
T <sub>DL</sub>	Data Valid Delay		20	25	ns	
T <sub>PW1</sub>	Pulse Width of SHD	10			ns	
T <sub>PW2</sub>	Pulse Width of SHD	10			ns	
T <sub>PIX</sub>	Pixel Period	37	56		ns	
т <sub>вк</sub>	Sample Black Aperture Delay		6		ns	$V_{DD} = 4.5V$ to 5.5V,
						Temperature -40°C to 85°C range
T <sub>VD</sub>	Sample Video Aperture Delay		5		ns	$V_{DD} = 4.5V$ to 5.5V,
						Temperature -40°C to 85°C range
T <sub>RST</sub>	RSTCCD Switch Delay	0		4	ns	$V_{DD} = 4.5V$ to 5.5V,
						Temperature -40°C to 85°C range
T <sub>SC</sub>	Shift Clock Period	50	100		ns	
T <sub>SET</sub>	Shift Register Setup Time	10			ns	
Latency	Pipeline Delay			4	cycles	
Power Supplie	S					
V <sub>DD</sub>	Analog Supply Voltage	4.5	5.0	5.5	V	
DV <sub>DD</sub>	Digital Output Supply Voltage	2.7	5.0	5.5	V	$DV_{DD} \le V_{DD}$ Always
I <sub>DD</sub>	Supply Current		50	75	mA	$DV_{DD} = V_{DD} = 5.0V (XRD9855)$
I <sub>DD27</sub>	Supply Current @ 27MHz		55	85	mA	F <sub>S</sub> = 27MHz (XRD9856)
I <sub>DDPD</sub>	Power Down Supply Current		50	100	μA	$\overline{\text{STBY1}} = 0 \text{ and } \overline{\text{STBY2}} = 0$





#### DC ELECTRICAL CHARACTERISTICS – XRD98L55 and XRD98L56

Unless otherwise specified:  $DV_{DD} = V_{DD} = 2.7V$ , Pixel Rate = 18MSPS,  $V_{RT} = 2.07V$ ,  $V_{RB} = 0.27V$ 

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
CDS Performa	ance					
CDSVIN	Input Range		200	800	$mV_{PP}$	Pixel (Black Level - Video Level)
BW	Small Signal Bandwidth (-3dB)		60		MHz	
SR	Slew Rate		40		V/µs	400mV Step Input
FT	Feed-through (Hold Mode)		-60		dB	
PGA Paramete	ers					
AV <sub>MIN</sub>	Minimum Gain	3.5	5	6.5	dB	
AV <sub>MAX</sub>	Maximum Gain	36.5	37	38.5	dB	
PGA n	Resolution		8		bits	Transfer function is linear steps in dB (1LSB = 0.125dB)
GE	Gain Error		5		% FS	At maximum or minimum gain setting
ADC Paramete	ers (Measured Through TESTVI	N)				
ADC n	Resolution	10			bits	
f <sub>s</sub>	Max Sample Rate	27			MSPS	
DNL	Differential Non-Linearity	-1	<u>+</u> 0.75	1.2	LSB	Up to 18MHz sample rate
						(XRD98L55)
DNL27	Differential Non-Linearity	-1	<u>+</u> 1.3	2.0	LSB	Up to 27MHz sample rate
						(XRD98L56)
EZS	Zero Scale Error	-50		50	mV	Measured relative to V <sub>RB</sub>
EFS	Full Scale Error			4	% FS	
V <sub>IN</sub>	DC Input Range	GND		$V_{DD}$	V	$V_{\rm IN}$ of the ADC can swing from GND to $V_{\rm DD}.~$ Input range is limited by the output swing of the PGA
V <sub>RT</sub>	Top Reference Voltage	1.2	2.07	$V_{DD}$	V	V <sub>RT</sub> >V <sub>RB</sub>
V <sub>RB</sub>	Bottom Reference Voltage	0.2	0.27	V <sub>DD</sub> -1	V	V <sub>RT</sub> >V <sub>RB</sub>
$\Delta V_{REF}$	Differential Reference Voltage	1.0	1.8	$V_{DD}$	V	
RL	Ladder Resistance	280	400	520	Ohms	
V <sub>RB</sub>	Self Bias $V_{RB} \left( V_{RB} = \frac{V_{DD}}{10} \right)$	0.20	0.30	0.40	v	$V_{\mbox{\scriptsize RB}}$ connected to $V_{\mbox{\scriptsize RBO}}$
V <sub>RT</sub>	Self Bias $V_{RT} \left( V_{RT} = V_{DD} \\ 1.30 \right)$	2.0	2.3	2.6	V	$V_{RT}$ connected to $V_{RTO.}$ T <sub>PW2</sub>

Rev. 1.01



#### DC ELECTRICAL CHARACTERISTICS – XRD98L55 and XRD98L56 (CONT'D) Unless otherwise specified: $DV_{DD} = V_{DD} = 2.7V$ , Pixel Rate = 18MSPS, $V_{RT} = 2.7V$ , $V_{RB} = 0.27V$

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
System Speci	fications					
DNLS	System DNL		1.0		LSB	XRD98L55 up to 18 MSPS
DNL <sub>S27</sub>	System DNL 27 MSPS		1.5		LSB	XRD98L56 up to 27 MSPS
INL <sub>SMIN</sub>	INL @ Minimum Gain		2		LSB	INL error is dominated by CDS/PGA linearity.
INL <sub>SMAX</sub>	INL @ Maximum Gain		2		LSB	INL error is dominated by CDS/PGA linearity.
V <sub>OS MINAV</sub>	Offset (Input Referred) @ Minimum Gain		5		mV	Offset is defined as the input pixel value -0.5 LSB required to cause the ADC output to switch from "Zero scale" to "Zero scale + 1LSB".
						Offset is measured after calibration.
V <sub>OS MAXAV</sub>	Offset (Input Referred) @ Maximum Gain		1		mV	Zero scale is the code in the offset register.
						Offset depends on PGA gain code.
en <sub>MAXAV</sub>	Input Referred Noise @ Maximum Gain		0.2		mV <sub>rms</sub>	Noise depends upon gain setting of the PGA.
en <sub>MINAV</sub>	Input Referred Noise @ Minimum Gain		0.7		mV <sub>rms</sub>	Noise depends upon gain setting of the PGA.
<b>Digital Inputs</b>			_			
V <sub>IH</sub>	Digital Input High Voltage	1.5			V	
V <sub>IL</sub>	Digital Input Low Voltage			0.7	V	
١ <sub>L</sub>	DC Leakage Current		5		μA	Input Between GND and $V_{DD.}$
C <sub>IN</sub>	Input Capacitance		5		pF	
Digital Outputs	S					
V <sub>OH</sub>	Digital Output High Voltage	DV <sub>DD</sub> -0.5			v	While sourcing 2mA.
V <sub>OL</sub>	Digital Output Low Voltage			0.5	V	While sinking 2mA.
I <sub>OZ</sub>	High-Z Leakage	-10		10	μA	$\overline{OE}$ =1 or $\overline{STBY1}$ = $\overline{STBY2}$ = 0. Output between GND & $DV_{DD}$ .



#### DC ELECTRICAL CHARACTERISTICS – XRD98L55 and XRD98L56 (CONT'D) Unless otherwise specified: $DV_{DD} = V_{DD} = 2.7V$ , Pixel Rate = 18MSPS, $V_{RT} = 2.07V$ , $V_{RB} = 0.27V$

Symbol	Parameter		Тур.	Max.	Unit	Conditions
Digital I/O Tim	ing					
T <sub>DL</sub>	Data Valid Delay		28	35	ns	
T <sub>PW1</sub>	Pulse Width of SHD	10			ns	
T <sub>PW2</sub>	Pulse Width of SHD	10			ns	
T <sub>PIX</sub>	Pixel Period	37	56		ns	
т <sub>вк</sub>	Sample Black Aperture Delay		7		ns	$V_{DD} = 2.7V$ to 3.6V,
						Temperature -40°C to 85°C range
T <sub>VD</sub>	Sample Video Aperture Delay		6		ns	$V_{DD} = 2.7V$ to 3.6V,
						Temperature -40°C to 85°C range
T <sub>RST</sub>	RSTCCD Switch Delay	0		5	ns	$V_{DD} = 2.7V$ to 3.6V,
						Temperature -40°C to 85°C range
T <sub>SC</sub>	Shift Clock Period	50	100		ns	
T <sub>SET</sub>	Shift Register Setup Time	10			ns	
Latency	Pipeline Delay			4	cycles	
Power Supplie	es					
V <sub>DD</sub>	Analog Supply Voltage	2.7	3.0	3.6	V	
DV <sub>DD</sub>	Digital Output Supply Voltage	2.7	3.0	3.6	V	$DV_{DD} \le V_{DD}$ Always
I <sub>DD</sub>	Supply Current		40	55	mA	$DV_{DD} = V_{DD} = 3.0 V (XRD9855)$
I <sub>DD27</sub>	Supply Current @ 27MHz		45	65	mA	F <sub>S</sub> = 27MHz (XRD9856)
I <sub>DDPD</sub>	Power Down Supply Current		50	100	μA	$\overline{\text{STBY1}} = 0 \text{ and } \overline{\text{STBY2}} = 0$

#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = +25 $^{\circ}$ C unless otherwise noted)<sup>1, 2, 3</sup>

V <sub>DD</sub> to GND	+7.0V	Lead Temperature (Soldering	g 10 seconds) 300°C
V <sub>RT</sub> & V <sub>RB</sub>	V <sub>DD</sub> +0.5 to GND -0.5V V <sub>DD</sub> +0.5 to GND -0.5V	Maximum Junction Tempera Package Power Dissipation F TOFP	ture 150°C Ratings ( $T_A$ = +70°C) $\theta_{1A} = 54°C/W$
All Inputs	V <sub>DD</sub> +0.5 to GND -0.5V V <sub>DD</sub> +0.5 to GND -0.5V	ESD.	
Storage Temperature	65°C to 150°C		

#### Notes:

<sup>1</sup> Stresses above those listed as "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

<sup>2</sup> Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082–2835) from input pin to the supplies. All inputs have protection diodes which will protect the device from short transients outside the supplies of less than 100mA for less than 100µs.

 $^{3}$  V<sub>DD</sub> refers to AV<sub>DD</sub> and DV<sub>DD</sub>. GND refers to AGND and DGND.

Rev. 1.01



#### SYSTEM DESCRIPTION

#### Correlated Double Sample/Hold (CDS) & Programmable Gain Amplifier (PGA); Gain [7:0]

The function of the CDS block, shown in *Figure 2*, is to sense the voltage difference between the black level and video level for each pixel. The CDS and PGA are fully differential. The PGA output is converted to a single ended signal, and then fed to the ADC. IN\_POS (CDS non-inverting input) should be connected, via a capacitor, to the CCD "Common" voltage. This is typically the CCD Reference output or ground. IN\_NEG (CDS inverting input) should be connected, via a capacitor, to the CCD output signal.

During the black reference phase of each pixel the SDRK switches are turned on, shorting the PGA1 inputs to  $V_{DD}$ . The sampling edge of SHP turns off the SDRK switches, sampling the black reference voltage on capacitors C1 & C2.

During the video phase of each pixel the SPIX switches are turned on. The difference between the pixel reference level and video level is transmitted through capacitors C1 & C2 and converted to a fully differential signal by the differential amplifier PGA1. The sampling edge of SHD turns off the SPIX switches, sampling the pixel value on capacitors C3 & C4.





Rev. 1.01







PGA1 provides gains of 0dB, 8dB & 16dB (1x, 2.5x, and 6.25x). The gain transitions occur at PGA gain codes 64d and 128d (40h & 80h). PGA2 provides gain from 6dB to 22dB (2x to 12.5x) with 0.125dB steps. *Figure 4* shows the measured PGA gain vs. Gain Code. The combined PGA blocks provide a programmable gain range of 32dB. The minimum gain (code 00h) is 6dB. The maximum gain (code FFh) is 38dB. The following equation can be used to compute PGA gain from the gain code:

$$Gain[dB] = 6 + \left(32 \times \frac{code}{256}\right)$$

where code is between 0 and 255. Due to device mismatch the gain steps at codes 63-64 and 127-128 may not be monotonic.



Figure 4. PGA Gain vs. Gain Code

Rev. 1.01

#### Analog-to-Digital Converter

The analog-to-digital converter is based upon a twostep sub-ranging flash converter architecture with a built in track and hold input stage. The ADC conversion is controlled by an internally generated signal, ADCLK (see *Figure 3*). The ADC tracks the output of the CDS/ PGA while ADCLK is high and holds when ADCLK is low. This allows maximum time for the CDS/PGA output to settle to its final value before being sampled. The conversion is then performed and the parallel output is updated, after a 2.5 cycle pipeline delay, on the rising edge of RSTCCD. The pipeline delay of the entire XRD9855/XRD9856 is 4 clock cycles.

The internal reference values are set by a resistor divider between  $V_{DD}$  and GND. To enable the internal reference, connect  $V_{RTO}$  to  $V_{RT}$  and connect  $V_{RBO}$  to  $V_{RB}$ . To maximize the performance of the XRD9855/XRD9856, the internal references should be used and decoupled to GND. Although the internal references have been set to maximize the performance of the CDS/PGA channel, some applications may require other reference values. To use external references, drive the  $V_{RT}$  pin directly with the desired voltage. Connect  $V_{RB}$  to  $V_{RBO}$ . Do not drive  $V_{RB}$  directly. The ADC parallel output bus is equipped with a high impedance capability, controlled by OE. The outputs are enabled when OE is low.

#### Automatic Offset Calibration, Offset [7:0]

To get the maximum color resolution and dynamic range, this part uses a digital controlled offset calibration system to compensate for external offset in the CCD signal as well as internal offsets of the CDS, PGA and ADC.

The calibration is performed every frame when the CCD outputs the Optical Black pixels, please see the section on Frame Timing. The Calibration logic compares the ADC output to the value stored in the serial port offset register, and increments or decrements the offset adjust DAC to make the ADC code equal to the code in the offset register. The first adjustment requires 8 pixels, then 6 pixels for subsequent adjustments. The offset register is 8 bits wide. Two MSBs set to 00 are added when compared to the 10-bit ADC code. After power-up the part may require up to 264 adjustments to converge on the proper offset. These adjustments can be made over many lines or frames. For example, with 20 optical black pixels per line, the calibration will make 3 adjustments per line, and initial convergence will require at most 88 lines



Graph 1. XRD9855 Typical Vdrk (CCD Offset) Calibration Range @ 25°C

Rev. 1.01





Figure 5. Automatic Offset Calibration Loop

#### Manual Global Offset, V [1:0]

In some systems the black level offset can be larger than the Automatic Offset Calibration Range. The XRD9855/XRD9856 provide a user programmable global offset adjustment which adds to the automatic offset calibration. The global offset is applied at the PGA input, so it's input referred value does not change with PGA gain code, see *Figure 6*. The magnitude of the global offset is controlled by bits V[1:0] in the mode register. (See *Table 1*.)

V[1]	V[0]	Offset
0	0	0mV
0	1	25mV (default)
1	0	50mV
1	1	75mV





#### Figure 6. Manual Global Offset & Automatic Offset Calibration

#### **Serial Interface**

A three wire serial interface, (LOAD, SCLK, and SDI), is used to program the PGA gain register, the Calibration offset register, the Mode control register, and the Aperture delay register. The shift register is 10 bits long. The first two bits loaded are the address bits that determine which of the four registers to update. The following eight bits are the data bits (MSB first, LSB last). When LOAD is high SCLK is internally disabled. Since SCLK is gated by LOAD, SCLK can be a continuously running clock signal, but this will increase system noise. To enable the shift register the LOAD pin must be pulled low. The data at SDI is strobed into the shift register on the rising edges of SCLK. When the LOAD signal goes high the data bits will be written to the register selected by the address bits (see *Figure 7*).

Rev. 1.01





Figure 7. Serial Port Timing Diagram

	Add	ress	Data								
Name	AD1	AD0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	
Gain	0	0	Gain[7]	Gain[6]	Gain[5]	Gain[4]	Gain[3]	Gain[2]	Gain[1]	Gain[0]	
Offset	0	1	Offset[7]	Offset[6]	Offset[5]	Offset[4]	Offset[3]	Offset[2]	Offset[1]	Offset[0]	
Mode	1	0	V[1]	V[0]	M3	M2	Test3	Test2	M1	Reset	
Delay	1	1	Dp[2]	Dp[1]	Dp[0]	Dd[2]	Dd[1]	Dd[0]	Dr[1]	Dr[0]	

#### Table 2. Serial Interface Register Address Map

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
	Gain [7:0]						
0000	0 0 0 0 0 0 0 - minimum gain (6dB) *						
1 1 1 1 1 1 1 - maximum gain (38 dB)							

#### Table 3. Gain Register Bit Assignment

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
	Offset [7:0]						
0000	0 0 0 0 0 0 0 - do not use						
0000	0 0 0 1 - do no	ot use					
0000	0 0 0 0 0 1 0 - minimum offset code						
0000	0 0 0 0 1 0 0 0 - default offset code, typical offset code 00100000						
0011	0 0 1 1 1 1 1 1 - maximum offset code						

#### Table 4. Offset Register Bit Assignment

Rev. 1.01



bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
V[1	:0]	М3	M2	Test3	Test2	M1	Reset
0 0 - 0m\	/ offset	0 - Clamp only*	0 - RSTCCD*	0 - TestVin off*	0 - test off*	0 - auto detect*	0 - normal*
0 1 - 25m	V offset*	1 - Clamp & Cal	1 - no RSTCCD	1 - TestVin on	1 - factory test	1 - manual	1 - reset
1 0 - 50mV offset							
1 1 - 75mV offset							

Table 5. Mode Register Bit Assignment

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
	Dp[2:0]		Dd[2:0]		Dd[2:0] Dr[1:0]		[1:0]
0 0 0 - SHP min delay *			0 0 0 - SHD min delay *			0 0 - RSTCC	D min delay *
1 1 1 - SHP max delay			1 1 1 - SHD max delay			1 1 - RSTCCD max delay	

#### Table 6. Delay Register Bit Assignment

#### Note:

\* Indicates default value

#### SHP, SHD and RSTCCD Signals, M2 = 0

The SHP input to the XRD9855/XRD9856 determines when the Black level of each pixel is sampled. For CLK\_POL=high timing mode, the black level is sampled on the falling edge of SHP. For CLK\_POL=low timing mode, the black level is sampled on the rising edge of SHP.

The sampling edge of SHP should be positioned so that it samples the pixel black level at a stable and repeatable point. The black level should be sampled after the CCD output has had time to settle from the reset pulse and before the output transitions to the video level (see *Figure 8*). Aperture delay  $T_{BK}$  needs to be taken into consideration when positioning the sampling edge of SHP (see *Figure 8*). This aperture delay is the time from the sampling edge of SHP to the time the pixel black level is actually sampled by the CDS. The correct positioning of SHP will be 6-7 ns prior to where the black level has adequately settled. This is typically just before the CCD signal starts the transition to the video level.

The SHD input to the XRD9855/XRD9856 determines when the Video level of each pixel is sampled. For CLK\_POL=high timing mode, the video level is sampled on the falling edge of SHD. For CLK\_POL=low timing mode, the video level is sampled on the rising edge of SHD.





The sampling edge of SHD should be positioned so that it samples the pixel video level at a stable and repeatable point. The video level should be sampled after the CCD output has settled from the black level and before the output transitions to the reset pulse. Aperture delay  $T_{vD}$  needs to be taken into consideration when positioning the sampling edge of SHD (see *Figure 8*). This aperture delay is the time from the sampling edge of SHD to the time the pixel video level is actually sampled by the CDS. The correct positioning of SHD will be 5-6 ns prior to where the video level has adequately settled. RSTCCD is intended to overlap the reset pulse of each pixel. This is intended to eliminate the reset pulse transients from getting into the CDS circuitry. Positioning of the RSTCCD signal so that it overlaps the CCD signal reset pulse is not always practical due to the timing generators being used or the frequency at which the CCD is running. The most critical thing to remember for RSTCCD is that it can not be high when sampling either the black level or video level.



Figure 8. CDS Timing Diagram (CLK\_POL = 1, M2 = 0)







Figure 9. Conversion Timing Diagram Showing Pipeline Delay (CLK\_POL = 1, M2 = 0)





#### **CDS Clock Polarity**

The CLK\_POL pin is used to determine the polarity of the CDS clocks (SHD, SHP, CLAMP). See *Figures 10 & 11, and Tables 7 & 8.* 

Event	Action
↑RSTCCD	Disconnect CDS Inputs from Reset Noise
↓RSTCCD	Connect CDS Inputs and Track Black Level
↓SHP	Hold Black Level and Track Video Level
↓SHD	Hold Video Level
1€10 \$10 \$10 \$10 \$10 \$10 \$10 \$10 \$10 \$10 \$	No Action
Clamp High	Activate DC Restore Clamp
Enable_Cal High	Activate Offset Calibration

Event	Action		
↑RSTCCD	Disconnect CDS Inputs from Reset		
	Noise		
↓RSTCCD	Connect CDS Inputs and Track Black		
	Level		
↑SHP	Hold Black Level and Track Video Level		
↑SHD	Hold Video Level		
↓SHP/SHD	No Action		
Clamp Low	Activate DC Restore Clamp		
Enable_Cal	Activate Offset Calibration		
High			

Table 7. Timing Event DescriptionTable Valid for CLK\_POL=1, M2=0

Table 8. Timing Event DescriptionTable Valid for CLK\_POL=0, M2=0



Figure 10. CCD Line Timing, CLK\_POL= 1, M2 = 0







Figure 11. CCD Line Timing with CLK\_POL = 0, M2 = 0

#### No RSTCCD Pulse Timing, M2 = 1

To help simplify the timing required to drive the XRD9855/XRD9856 we have included a timing mode which does not require an active signal for RSTCCD. To use this timing, bit M2 in the timing mode register must be set high.

In this timing mode, RSTCCD must be kept low. No changes are required for the timing of the SHP and SHD signals. The polarity of SHP, SHD and Clamp are still controlled by the CLK\_POL pin. The digital outputs change on the sampling edge of SHD (see *Figure 12*). This mode can be used with both the XRD4460 and XRD9853 compatible timing as described in the Line Timing section. Data output DB[9:0} is delayed as SHD is delayed with the delay feature AD[1:0] = [1,1].





### Programmable Aperture Delays Dp[2:0], Dd[2:0], Dr[1:0]

To help fine tune the pixel timing, the XRD9855/ XRD9856 allows the system to adjust the aperture delays associated with SHP ( $T_{BK}$ ), SHD ( $T_{VD}$ ) and RSTCCD ( $T_{RST}$ ) by programming the Aperture Delay serial port register. On power up these three aperture delays are set to their minimum values.

The SHP aperture delay is set by bits Dp[2:0]. Each LSB adds approximately 2ns of delay. The SHD aperture delay is set by bits Dd[2:0]. Each LSB adds approximately 2ns of delay. The RSTCCD aperture delay is set by bits Dr[1:0]. Each LSB adds approximately 4ns of delay.

Dp[2]	Dp[1]	Dp[0]	SHP Aperture Delay T <sub>BK</sub> (typ)
0	0	0	6ns (default)
0	0	1	8ns
0	1	0	10ns
0	1	1	12ns
1	0	0	14ns
1	0	1	16ns
1	1	0	18ns
1	1	1	20ns

Table 9. Programmable SHP Delays

Dd[2]	Dd[1]	Dd[0]	SHD Aperture
			Delay T <sub>VD</sub> (typ)
0	0	0	5ns (default)
0	0	1	7ns
0	1	0	9ns
0	1	1	11ns
1	0	0	13ns
1	0	1	15ns
1	1	0	17ns
1	1	1	19ns

Table 10. Programmable SHD Delays

Dr[1]	Dr[0]	RSTCCD Aperture Delay T <sub>RST</sub> (typ)
0	0	3ns (default)
0	1	7ns
1	0	11ns
1	1	15ns

Table 11.	Programmable RSTCCD Delays	5
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#### Line Timing with Frame Calibration

At the beginning and/or end of every CCD frame there are a number of Optical black lines. The XRD9855/ XRD9856 uses the output from these pixels for the DC Restore Clamp and Black Level Offset Calibration functions. These functions are controlled by the Clamp and/or EnableCal pins.

The XRD9855/XRD9856 is designed to be compatible with the Clamp Only timing of the XRD4460 or the Clamp & EnableCal timing of the XRD9853. On power up the chip will automatically detect which timing is being used and make the necessary internal adjustments. If EnableCal is high when Clamp is active, then "Clamp Only" timing is selected (M3=0). If EnableCal is low when Clamp is active, then "Clamp & Cal" timing is selected (M3=1). If required, the automatic detection function can be disabled through the serial port, and the chip can be forced into one of the two timing modes by programming mode register bits M3 & M1. Frame clibration however, can only be used with m3=0.

To maximize dynamic range in the dark areas of an image the PGA black level output must be equal to the bottom reference voltage of the ADC. This ensures that a dark pixel input corresponds to a desired minimum code output from the XRD9855 and XRD9856.

The XRD9855 and XRD9856 use the Optically Black (OB) pixels on a CCD array to calibrate for itself and the CCD. Figure 13 shows the outline of a typical CCD. The shaded region on the outside of the array indicates the position of the optically black (OB) pixels. The center region indicates the position of the active pixels used for an image.

Rev. 1.01



### Figure 13. Typical Outline of an Area Array CCD.

The CCD has many OB pixels available for use in calibration. Some are available at the start and end of each line while whole lines of OB pixels are available at the top and bottom of the array.

The XRD9855 and XRD9856 take advantage of the large number of OB pixels available at the top and bottom of the CCD array to perform calibration before any active pixels are processed.

The XRD9855 and XRD9856 use a digital feedback loop to achieve auto-calibration. The output of the ADC and a desired dark code programmed in the offset register are compared during the OB pixel output from the CCD. The recommended offset register value is 32 decimal. The difference determines whether the offset adjustment DAC increments or decrements. This adjusts the offset of the PGA to achieve the desired ADC output code for a dark pixel input.

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The first adjustment requires 8 cycles of SHP/SHD clocks but every subsequent adjustment requires only 6 cycles: 1 cycle for CDS, 3 cycles for A/D conversion, 1 cycle for logic, and 1 cycle for DAC update, see Figure 14. When Enable\_Cal pin is low, the offset calibration logic is disabled, and the current state of the offset DAC is held constant.

The XRD9855 and XRD9856 calibration time depends on the calibration method and the number of OB pixels available. The time required to achieve calibration, in frame calibration, depends on the number of OB pixels present in each line.

Using Frame calibration, calibration can be achieved after several lines depending upon the number of OB pixels at the top or bottom of an array. Enable\_Cal must be generated by the timing generator to properly frame the optical black lines.



Figure 14. XRD9855 and XRD9856 Offset Calibration Timing, M3 = 1

Rev. 1.01



Frame calibration uses the OB *lines* available at the start and end of the array, see the dark shaded regions at the top and bottom of Figure 15, to perform its auto-calibration.

The dark shaded regions of Figure 15 are the OB lines at the start and end of the CCD array. Typically, these OB lines are the largest blocks of OB pixels available on the array. Using these areas will allow the XRD9855 and XRD9856 to achieve calibration before any active pixels are processed. This means that the XRD9855 and XRD9856 can achieve calibration for the very first frame if OB lines are used for calibration at the start of the array. The timing needed for Frame Calibration Mode is shown in Figure 16. In Frame Calibration Mode, Enable\_Cal needs to be active during the OB line output from the CCD. Enable\_Cal gates the XRD9855 and XRD9856's auto-calibration logic and must never be high when CLAMP is active. Clamp still needs to be active once a line, either during start of line or end of line OB pixels.

Frame calibration is useful for applications where fast calibration is needed. With frame calibration, the XRD9855 and XRD9856 can achieve calibration before the first frame is started.



Figure 15. OB Lines Used For Frame Calibration on a Typical CCD Array



Rev. 1.01

#### *Clamp Only Timing (XRD4460 compatible) M1=1, M3=0, NOT RECOMMENDED*

In this mode EnableCal is held high, and Clamp is activated during the Optical Black pixels. While this mode is available, it is not recommended for best performance. This timing does not perform frame calibration. The Clamp signal is used to trigger a one-shot which controls the internal DC restore switch and the calibration logic. The DC restore switch is turned on for two pixels after Clamp is activated. Then the Calibration logic is enabled and runs until Clamp is deactivated. The chip can be forced into this timing mode by programming the Mode control register bits M1=1 and M3=0.







#### Clamp & EnableCal Timing (XRD9853 Compatible) M1=1, M3=1

In this mode EnableCal must be active during the large number of Optical Black pixels (usually at the end of each CCD line or at the start of a frame), Clamp should be active during the Dummy pixels (usually at the beginning of each CCD line).

The EnableCal pin (always active high) directly controls the calibration logic. The Clamp pin (polarity determined by CLK\_POL) controls only the DC restore switch at the CDS input. EnableCal and Clamp must not be active at the same time. Clamp must be used every line.

The chip can be forced into this timing mode by programming the Mode control register bits M1=1 and M3=1.



Figure 19. Clamp & EnableCal Timing, CLK\_POL=1, M1=1, M3=1, M2=0









M1=1, M3=3

#### Stand-by Mode (Power Down)

The STBY1 and STBY2 pins are used to put the chip into the Stand-by or Power down mode. In this mode all sampling and conversion stops, The digital outputs are put into the high impedance mode, and the power supply current will drop to less than  $50\mu$ A.

For most applications STBY1 and STBY2 should be connected together and treated as a single control pin. If an application uses the TestVin pin to access the PGA output or the ADC input then STBY1 and STBY2 must be separately controlled, see the truth table below.

STBY2	STBY1	CDS/ PGA	ADC	Clock Inputs	Digital Outputs
0	0	Off	Off	Off	High-z
1	0	On	Off	On	High-z
0	1	Off	On	On	On
1	1	On	On	On	On

Table 12.	Stand-by	<b>Truth Table</b>
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#### **Chip Reset**

The chip has an Internal Power-On-Reset function to ensure all internal control registers start up in a known state. Pulling the Reset pin high or writing a logic 1 to the Mode Registers reset bit will also reset the chip to the Power-up default conditions.

Register	Default	Notes
Gain[7:0]	00000000	minimum gain
OS[7:0]	00001000	code 08 hex
V[1:0]	01	25 mV offset
М3	0	Clamp only
M2	0	RSTCCD required
M1	0	Automatic timing detect On
Test3	0	Test modes off
Test2	0	Test modes off
Reset	0	reset bit will reset itself
Dp[2:0]	000	minimum delay
Dd[2:0]	000	minimum delay
Dr[1:0]	00	minimum delay

Table 13. Reset Conditions

#### Using TestVin (Pin 20)

The TestVin pin allows access to the input of the ADC, or it can be used to monitor the CDS/PGA output. The TestVin pin accesses the ADC input node through switch S1 (see *Figure 18*). This switch is controlled by Bit3 of the serial port Test register. When the TEST3 bit of the mode register is high, switch S1 is "ON" and the TestVin pin can be used to access the ADC input/PGA output. When the TEST3 bit of the mode register is low, switch S1 is "OFF" and the TestVin pin is disconnected from the ADC input/PGA output.

<u>To use TestVin as an</u> auxiliary ADC input force STBY2=low and STBY1=high. This will disable the CDS/PGA and leave the ADC operating. If M2=0, the ADC clock is generated from RSTCCD and SHP (*See Figure 19*). If M2=1, the ADC clock is generated from SHP & SHD (*See Figure 20*).





Figure 21. Using TestVin to Access PGA Output & ADC Input

Mode Reg.	AD1	AD0	V[1]	V[0]	M3	M2	Test3	Test2	M1	Reset
TestVin	1	0	0	0	0	1	1	0	0	0
Normal	1	0	0	0	0	1	0	0	0	0

Table 14. Serial Port Data to Use TestVin





Figure 23. ADC Clock Generation, CLK\_POL=1, M2=1





#### **Digital Output Power Supplies**

The DV<sub>DD</sub> and DGND pins supply power to the digital output drivers for pins DB[9:0], UNDER, and OVER. DV<sub>DD</sub> is isolated from V<sub>DD</sub> so it can be at a voltage level less than or equal to V<sub>DD</sub>. This allows the digital outputs to interface with advanced digital ASICs requiring reduced supply voltages. For example V<sub>DD</sub> can be 5.0 or 3.3V, while DV<sub>DD</sub> is 2.5V.

#### **Power Supply Sequencing**

There are no power supply sequencing issues if  $DV_{DD}$  and  $V_{DD}$  of the XRD9855/XRD9856 are driven from the same supply. When  $DV_{DD}$  and  $V_{DD}$  are driven separately,  $V_{DD}$  must come up at the same time or before  $DV_{DD}$ , and go down at the same time or after  $DV_{DD}$ . If the power supply sequencing in this case is not followed, then damage may occur to the product due to current flow through the source-body junction diodes between  $DV_{DD}$  and  $V_{DD}$ . An external diode (5082-2235) layed out close to the converter from  $DV_{DD}$  to  $V_{DD}$  prevents damage from occurring when power is cycled incorrectly.

**Note:**  $V_{DD}$  must be greater than or equal to  $DV_{DD}$  or the source-body diodes will be forward based.



Figure 24.  $DV_{DD}$  & DGND Digital Output Power Supplies,  $V_{DD} \ge DV_{DD}$ 



#### **General Power Supply and Board Design Issues**

All of the GND pins, including DGND, should be connected directly to the analog ground plane under the XRD9855/XRD9856. The  $V_{DD}$ 's should be supplied from a low noise, well filtered regulator which derives the power supply voltage from the CCD power supply. All of the  $V_{DD}$  pins are analog power supplies and should be locally decoupled to the nearest GND pin with a 0.1µF, high frequency capacitor.  $DV_{DD}$  is the power supply for the digital outputs and should be locally decoupled.  $DV_{DD}$  should be connected to the same power supply network as the digital ASIC which receives data from the XRD9855/XRD9856.

In general, all traces leading to the XRD9855/XRD9856 should be as short as possible to minimize signal crosstalk and high frequency digital signals from feeding into sensitive analog inputs. The two CCD inputs, In\_Pos and In\_Neg, should be routed as fully differential signals and should be shielded and matched. Efforts should be made to minimize the board leakage currents on In\_Pos and In\_Neg since these nodes are AC coupled from the CCD to the XRD9855/XRD9856. The digital output traces should be as short as possible to minimize the capacitive loading on the output drivers (see *Figure 25*)





#### **Application Note**

If increasing the PGA Gain to code 128 (80h) or higher causes a larger than expected offset increase in the ADC digital output codes, the problem may be due to the limited Automatic Offest Calibration range. This problem may be solved by increasing the Global Offset code, V[1:0], in the Mode Register. The default is V[1:0] = 01 (binary). Try increasing to V[1:0] = 10, or V[1:0] = 11. For additional information on the XRD9855 feaures:

- Auto-detect
- EnableCal & Clamp Line Timing
- Clamp Only Line Timing
- Digital Clibration Loop
- Dark Voltage Calibration Range

Please see Application Notes XRDAN109, XRDAN110, XRDAN112, XRDAN113 and XRDAN114.













Figure 27. Input Reference Noise vs. PGA Gain Codes







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Figure 28. XRD98L55 Input Referred Noise





#### 48 LEAD THIN QUAD FLAT PACK (7 x 7 x 1.4 mm TQFP) rev. 2.00



	INC	HES	MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	
A	0.055	0.063	1.40	1.60	
A1	0.002	0.006	0.05	0.15	
A2	0.053	0.057	1.35	1.45	
В	0.007	0.011	0.17	0.27	
С	0.004	0.008	0.09	0.20	
D	0.346	0.362	8.80	9.20	
D1	0.272	0.280	6.90	7.10	
е	0.020 BSC		0.50 BSC		
L	0.018	0.030	0.45	0.75	
а	0×	7×	0×	7×	

Rev. 1.01



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